## Abstract of the Disclosure

A heatsink for dissipating heat from a heat-generating source such as an electronic component includes heatsink plates, wherein the individual heatsink plates are bound together at a binding portion to form a heat-absorbing portion for contacting a heat-dissipating surface of the electronic component, and portions of the heatsink plates opposite the heat-absorbing surface are separated from each other to collectively act as a heat-dissipating portion binding the heatsink plates together. To provide the separation between heat-dissipating portions of the heatsink plates, the heatsink includes spacers interposed between the binding portions of neighboring heatsink plates or the heatsink plates are spread out apart from each other by being bent at angles. The heatsink plates include fins spaced apart from each other at an interval. The binding element is preferably a rivet. In manufacturing the heatsink, a protrusion is formed at the individual heatsink plates such that the heat dissipating portion of the heatsink is unfolded outward at a angle by the protrusion. The heatsink can transfer the heat generated from a heat-generating source into the surrounding air, without power consumption and without generation of noise and vibrations, and such a heatsink can easily be manufactured.